

Claims

1. Anode for electroplating, which comprises an anode base and a shield, wherein the anode base comprises a support material and a substrate with active layer, and wherein the shield is attached to the anode base at a distance from it and reduces material transport to and from the anode base.
2. Anode according to claim 1, in which the support material is self-passivating under electrolysis conditions.
3. Anode according to claim 1 or 2, in which the active layer is electron-conducting.
4. Anode according to any one of claims 1 to 3, in which the shield consists of plastic.
5. Anode according to any one of claims 1 to 3, in which the shield consists of metal.
6. Anode according to claim 5, in which the shield consists of a metal grid, an expanded metal or a perforated plate.
7. Anode according to any one of claims 1 to 3, in which the shield consists of plastic and metal.
8. Anode according to any one of claims 1 to 7, in which the shield is connected to the anode base in an electric current-conducting manner.
9. Anode according to any one of claims 1 to 8, in which the shield is at a distance of 0.01 to 100 mm, preferably 0.05 to 50 mm, particularly preferably 0.1 to 20 mm and quite particularly preferably 0.5 to 10 mm, from the anode base.
10. Anode according to any one of claims 1 to 9, in which the

form of the shield, the arrangement and the distance from the anode base are such that the gas bubbles forming at the anode during electroplating are brought together.

11. Anode according to any one of claims 1 to 10, which is connected as a cathode.
12. Electroplating process, in which an anode according to any one of claims 1 to 11 is used.
13. Use of an anode according to any one of claims 1 to 11 for electroplating.
14. Anode for electroplating, which has a support material and an active layer, wherein the active layer has two ends and the surface area of the active layer decreases from the one end, which is essentially on top in operation, to the other end, which is essentially underneath in operation.
15. Anode according to claim 14, in which the active layer is attached directly to the support material.
16. Anode according to claim 14, in which the active layer is applied to a substrate and this substrate is attached to the support material.
17. Anode according to any one of claims 14 to 16, which is connected as a cathode.
18. Electroplating process, in which an anode according to any one of claims 14 to 17 is used.
19. Use of an anode according to any one of claims 14 to 17 for electroplating.